

02-02-2004

To the Honorable Assistant Secretary and Comptroller thereof.

Please record the attached original document.



102659038

1. Name of conveying party(ies):

Sunji ICHIKAWA

2. Name and address of receiving party(ies):

Name: Oki Electric Industry Co., Ltd.

Street Address: 7-12, Toranomon 1-chome, Minato-ku, Tokyo, Japan

Additional name(s) of conveying party(ies) attached? NO

Additional name(s) & address(es) attached? NO

3. Nature of conveyance:

☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other

Execution Date: December 4, 2003

4. Application number(s) or patent number(s):

10763227

If this document is being filed together with a new application, the execution date of the application is: December 4, 2003

A. Patent Application No.(s)
NEW, filed January 26, 2004

B. Patent No.(s)

Additional numbers attached? NO

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: WENDEROTH, LIND & PONACK, L.L.P.
Attn: Nils E. Pedersen, Esq.

Street Address: 2033 K Street, N.W., Suite 800

City: Washington, State: DC ZIP: 20006-1021

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41). \$40.00

☒ Enclosed (Check No. 59864)
Authorized to be charged to deposit account

8. Deposit account number: 23-0975

(Attach duplicate copy of this page if paying by deposit account)

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Nils E. Pedersen, Reg. No. 33,145
Name of Person Signing

Signature

January 26, 2004
Date

Total number of pages including cover sheet: 2

OMB No. 0651-0011 (exp. 4/94)

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01/29/2004 RMEBRAHT 00000042 10763227

DE FC:8021

40.00 DP

ASSIGNMENT OF APPLICATION FOR UNITED STATES LETTERS PATENT

WHEREAS Sunji ICHIKAWA

hereinafter referred to collectively as the assignor, has invented a certain improvement relating to LEAD FRAME, MANUFACTURING METHOD OF THE SAME, AND SEMICONDUCTOR DEVICE USING THE SAME

☒ the inventor(s) declaration for said application being executed concurrently with the execution of this instrument; said application to be filed in the United States Patent and Trademark Office;

☐ said application having been filed in the United States Patent and Trademark Office on, _____ authorization being hereby given to my attorneys, **Michael R. Davis, Matthew M. Jacob, Jeffrey Noltan, Warren M. Cheek, Jr, Charles R. Watts and Nils E. Pedersen** of **WENDEROTH, LIND & PONACK, L.L.P.**, 2033 K Street, N.W., Suite 800 Washington, D.C. 20006, to insert here in parentheses (Application Serial No. _____) the application serial number of said application when known;

☐ said application having been filed under the Patent Cooperation Treaty on _____, Serial No.) _____, the United States of America being designated.

AND WHEREAS Oki Electric Industry Co., Ltd.

of 7-12, Toranomom 1-chome, Minato-ku, Tokyo, Japan

hereinafter referred to as the assignee, is desirous of acquiring the entire right, title and interest in and to said application, including any and all divisions and continuations thereof, and in and to said invention and any and all patents which may be granted therefor, including any and all renewals, reissues and prolongations thereof;

NOW THIS WITNESSETH, that for and in consideration of One Dollar (\$1.00), and other good and valuable consideration paid by said assignee to said assignor, the receipt of which is hereby acknowledged, said assignor hereby assigns, sells and transfers to said assignee, and said assignee's successors and assigns, the full and exclusive right, title and interest in and to said application, including any and all divisions and continuations thereof, and in and to said invention and any and all patents which may be granted therefor, including any and all renewals, reissues and prolongations thereof; said assignee, and said assignee's successors and assigns, to have, hold, exercise and enjoy the said application, including any and all divisions and continuations thereof, and the said invention and any and all patents which may be granted therefor, including any and all renewals, reissues and prolongations thereof, with all the rights, powers, privileges and advantages in anywise arising from or appertaining thereto, for and during the term or terms of any and all such patents when granted, including any and all renewals, reissues and prolongations thereof, for the use and benefit of said assignee, and said assignee's successors and assigns, in as ample and beneficial a manner as the said assignor might or could have held and enjoyed the same, if this assignment had not been made.

AND said assignor hereby agrees to perform, upon the request of said assignee, or said assignee's successors or assigns, any and all acts relating to the obtaining or to the asserting of said patents, including any and all renewals, reissues and prolongations thereof.

AND said assignor authorizes and requests the Commissioner of Patents and Trademarks to issue Letters Patent on said application, and on any and all divisions and continuations thereof, to said assignee, and said assignee's successors and assigns, in accordance herewith.

EXECUTED, December 4 . 2003

WITNESS:

ASSIGNOR:

Signature: Makoto Terui

Signature: Sunji Ichikawa

Name: Sunji ICHIKAWA

WENDEROTH, LIND & PONACK, L.L.P.